EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7	"6335563"	USPAT; JPO	OR	OFF	2006/09/25 14:01
L2	814	257/632	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 14:03
L5	12	("4561011" | "5396403" | "5459352" | "5587882" | "5926371" | "5931222" | "6008536" | "6188578" | "6462410" | "6469380" | "6504243" | "6656770").PN. OR ("6882535").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:16
L6	12	("5357404" | "5552635" | "5585671" | "5594624" | "5651688" | "5745344" | "5777852" | "5847928" | "5850691" | "5907474" | "5990552" | "6108207").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:19
L7	18	("4868349" | "5233225" | "5289039" | "5294826" | "5397746" | "5489801" | "5608267" | "5652461" | "5653891" | "5892278" | "6093960" | "6104093" | "6229702" | "6369455").PN. OR ("6469380").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:20
L8	27	("4914551" | "5459352" | "5504652" | "5710459" | "5870285" | "5898571" | "5920458" | "5926371" | "5933324" | "6008536").PN. OR ("6188578").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:30
L9	2	"20020079573".pn. or "20030180484".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:30
L12	23	("5817545" | "5866949" | "5868887" | "5900312" | "5909057" | "5953814" | "5959348" | "5981312" | "6015722" | "6083774" | "6124643" | "6163463" | "6187613" | "6191952" | "6207475" | "6232152").PN. OR ("6309908").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:51

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L13	28	("3795884" | "3951495" | "4190879" | "4553192" | "4620761" | "4630172" | "4688151" | "5012386" | "5088930" | "5120678" | "5157480" | "5202288" | "5216278" | "5280409" | "5282111" | "5285352" | "5291062" | "5298686" | "5309324" | "5324205" | "5403776" | "5455456" | "5557504" | "5570273").PN. OR ("6113399").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:56
L14	25	("3986251" | "4035830" | "4147889" | "4181249" | "4293587" | "4321617" | "4323914" | "4434434" | "4451972" | "4535219" | "4772935" | "4866505" | "5161728" | "5183972" | "5230924" | "5248079" | "5392982" | "5672548" | "5847929" | "5909056" | "5942794" | "5990418" | "6013109" | "6197619" | "6376907").PN. OR ("6492724").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:57
L15	27	("4914551" | "5459352" | "5504652" | "5710459" | "5870285" | "5898571" | "5920458" | "5926371" | "5933324" | "6008536").PN. OR ("6188578").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 14:59
L16	18	("4151547" | "5041902" | "5111359" | "5247426" | "5537342" | "5619070" | "5625226" | "5705851" | "5726079" | "5736785" | "5760465" | "5777847" | "5868887" | "5883430").PN. OR ("6507116").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:01
L17	19	("5022462" | "5200809" | "5249101" | "5371652" | "5386144" | "5510956" | "5602719" | "5789813" | "5886876" | "5901041" | "6008536").PN. OR ("6373703").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:08

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L18	12	("4611389" | "5157478" | "5250843" | "5311060" | "5353498" | "5450283" | "5497033" | "5525834" | "5592735" | "5672548" | "5879794" | "5938854").PN. OR ("6576996").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:09
L19	44	("4825284" | "5073817" | "5108955" | "5172213" | "5371404" | "5396403" | "5450283" | "5619070" | "5672548" | "5883430" | "5892289").PN. OR ("6104093").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:17
L21	12	("4855867" | "5510956").PN. OR ("5917702").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:56
L22	17	("4147889" | "4742024" | "5107329" | "5381039" | "5623394" | "5909056" | "5931222" | "5990418" | "6008536").PN. OR ("6376907").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:06
L23	19	("5475040" | "5583378" | "5786631" | "5834337" | "5843810" | "5891755" | "5907189" | "5910010" | "5930893" | "6011304" | "6175157" | "6215180" | "6218202").PN. OR ("6424033").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:07
L25	10	("5144412" | "5378924" | "5977626" | "5990418" | "6162663" | "6462405" | "6528876" | "6599779" | "6617200" | "6677185").PN. OR ("6921974").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:09
L26	11	("4617586" | "5055704" | "5710071" | "5864470" | "5866942" | "6104093" | "6160705" | "6228681" | "6259587" | "6396136" | "6407432").PN. OR ("6995037").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:30
L27	13	silane near coupler with filler	USPAT	OR	OFF	2006/09/25 15:30
L28	49	("4835598" | "5397917" | "5450290" | "5467253" | "5561322" | "5592025" | "5619070" | "5640047").PN. OR ("5866942").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:43

L29	7	("4814943" | "5367435" | "5483099" | "5510956" | "5552635" | "5898219" | "5917702").PN. OR ("6110762"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 15:59
L30	20	("4814943" | "5367435" | "5483099" | "5552635").PN. OR ("5898219").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:00
L31	17	("5329423" | "5435732" | "5610442" | "5736785" | "5877552" | "5898219" | "5901043" | "5977626" | "5985695" | "6016013" | "6075712" | "6175161" | "6181569" | "6388335" | "6462405").PN. OR ("6737755"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:02
L32	22	("20010019181" | "5216278" | "5610442" | "6198171" | "6246115").PN. OR ("6462405"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:03
L33	8	("5482898" | "5598321" | "5977626" | "6008536" | "6208519" | "6246115").PN. OR ("6528876").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:13
L35	374	(semiconductor or die or chip or dice or IC) and (mold$3 or encapsulat$3 or cover$3 near (plastic or resin)) with (heat$3 or thermal) with (adhes$3 or greas$3 or oil or attach$3 or glu$3) and (heat$3 or thermal) with (adhes$3 or greas$3 or oil or attach$3 or glu$3) with (filler or particles or powder$3)	USPAT	OR	OFF	2006/09/25 17:04
L36	125	("4680617" | "4788583").PN. OR ("5641997").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:55
L37	105	silicon$1 with PSA with rubber	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:57
L38	0	silicon$1 with PSA with rubber with filler	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:56
L39	0	silicon$1 with PSA with rubber same filler	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:56

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L40	0	silicon$1 with PSA with rubber same particles	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:56
L41	1	silicon$1 with PSA with rubber same powder	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:56
L42	28	silicon$1 near PSA with rubber	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/25 16:57
L43	27537	(semiconductor or die or chip or dice or IC) with pack$3 and (cap or lid or heat or thermal)	USPAT	OR	OFF	2006/09/25 17:05
L44	13829	(semiconductor or die or chip or dice or IC) with pack$3 and (mold$3 or encapsulat$3) and (cap or lid or heat or thermal)	USPAT	OR	ON	2006/09/25 17:06
L45	4287	(semiconductor or die or chip or dice or IC) with pack$3 and (mold$3 or encapsulat$3) same (adhes$3 or glu$3 or grease or oil) and (cap or lid or heat or thermal)	USPAT	OR	ON	2006/09/25 17:07
L46	2011	(semiconductor or die or chip or dice or IC) with pack$3 and (mold$3 or encapsulat$3) same (adhes$3 or glu$3 or grease or oil) same (cap or lid or heat or thermal)	USPAT	OR	ON	2006/09/25 17:08
L47	17	(semiconductor or die or chip or dice or IC) with pack$3 and (mold$3 or encapsulat$3) same (adhes$3 or glu$3 or grease or oil) same (cap or lid or heat or thermal) and (adhes$3 or glu$3 or grease or oil) with silicon$1 near rubber with (filler or particles or powder)	USPAT	OR	ON	2006/09/25 17:19
L48	13	35 and silicon$1 near rubber with (filler or particles or powder)	USPAT	OR	ON	2006/09/25 17:15
L49	14	(semiconductor or die or chip or dice or IC) with pack$3 and (mold$3 or encapsulat$3) same (adhes$3 or glu$3 or grease or oil) same (cap or lid or heat or thermal) and (adhes$3 or glu$3 or grease or oil) with silicon$1 near rubber with (filler or particles or powder)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 17:19

L50	1	257/E23.119	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:10
L51	4	257/E23.087	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:10
L52	11	257/E23.101	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:11
L53	3000	257/706	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:18
L54	1609	257/704	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:40
L55	1012	257/720	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:53
L56	3804	257/738	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 18:58

L57	4261	257/723	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 19:05
L58	814	257/632	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 19:30
L59	2	"6107679".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 19:18
L60	400	(semiconductor or die or dice or chip or IC) and mounting near substrate with resin	USPAT	OR	OFF	2006/09/25 19:19
L61	8	(semiconductor or die or dice or chip or IC) and mounting near substrate with resin and mounting near substrate with single near layer	USPAT	OR	OFF	2006/09/25 19:20
L62	8	(semiconductor or die or dice or chip or IC) and mounting near substrate with resin and mounting near substrate with single near layer	USPAT	OR	ON	2006/09/25 19:20
L63	582	257/790	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 19:48
L64	1154	257/717	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:01

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L65	1604	257/718	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:26
L66	1538	257/719	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:40
L67	1144	438/122	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:45
L68	2740	438/118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:51
L69	3673	174/52.4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/25 20:51
S1	9	"61102757" or "61019154" or "60154543" or "6433412" or "6492724" or "6737755" or "6724061"	USPAT; JPO	OR	OFF	2004/09/07 03:27
S2	294	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) and thermal near grease and (mold$3 or encapsulat$3)	USPAT; JPO	OR	OFF	2004/09/07 04:11
S3	265	(semiconductor or die or chip or IC) and heat same thermal near grease and (mold$3 or encapsulat$3)	USPAT; JPO	OR	OFF	2004/09/07 04:14

EAST Search History

S4	63	(semiconductor or die or chip or IC) and (lid or cap) same thermal near grease and (mold$3 or encapsulat$3)	USPAT; JPO	OR	ON	2004/09/07 06:13
S5	159	(semiconductor or die or chip or IC) and (lid or cap) and thermal near grease and (mold$3 or encapsulat$3)	USPAT; JPO	OR	ON	2004/09/07 06:20
S6	96	((semiconductor or die or chip or IC) and (lid or cap) and thermal near grease and (mold$3 or encapsulat$3)) not ((semiconductor or die or chip or IC) and (lid or cap) same thermal near grease and (mold$3 or encapsulat$3))	USPAT; JPO	OR	ON	2004/09/07 06:13
S7	339	(semiconductor or die or chip or IC) and heat and thermal near grease and (mold$3 or encapsulat$3)	USPAT; JPO	OR	ON	2004/09/07 07:00
S8	778	(semiconductor or die or chip or IC) and heat and thermal near grease	USPAT; JPO	OR	ON	2004/09/07 07:54
S9	439	((semiconductor or die or chip or IC) and heat and thermal near grease) not ((semiconductor or die or chip or IC) and heat and thermal near grease and (mold$3 or encapsulat$3))	USPAT; JPO	OR	ON	2004/09/07 07:01
S10	314	(semiconductor or die or chip or IC) and (lid or cap) and thermal near grease	USPAT; JPO	OR	ON	2004/09/07 07:54
S11	5	"5977633".pn. or "5223741".pn. or "5585671".pn. or "6462410". pn. or "4748495".pn.	USPAT	OR	OFF	2004/09/07 08:30
S12	64	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) and thermal near grease and (mold$3 or encapsulat$3) and (silicon or "Si") with chip	USPAT	OR	OFF	2004/09/07 09:19
S13	21	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) with (copper or "Cu") and thermal near grease and (mold$3 or encapsulat$3) and (silicon or "Si") with chip	USPAT	OR	OFF	2004/09/07 09:19
S14	2440	257/738	USPAT	OR	OFF	2004/09/08 12:05

EAST Search History

S15	2775	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/08 15:48
S16	20	"5785799"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/08 15:56
S17	1570	(mold$3 or encapsulat$3) with curing near agent	USPAT	OR	OFF	2004/09/08 19:43
S18	5	((mold$3 or encapsulat$3) with curing near agent) and (semiconductor or die or chip or IC) and heat near sink with ("Cu" or copper)	USPAT	OR	OFF	2004/09/08 19:46
S19	9	((mold$3 or encapsulat$3) with curing near agent) and (semiconductor or die or chip or IC) and heat near sink with ("Cu" or copper or aluminum or "Al")	USPAT	OR	OFF	2004/09/10 19:43
S20	0	thermal near grease with (silicon near rubber and particles)	USPAT	OR	ON	2005/09/01 13:45
S21	0	thermal near grease with silicon near rubber with particles	USPAT	OR	ON	2004/09/10 19:45
S22	3	thermal near grease with silicon near rubber	USPAT	OR	ON	2004/09/10 19:46
S23	0	thermal near grease same (silicon near rubber and particles)	USPAT	OR	ON	2004/09/10 19:46
S24	11	thermal near grease same silicon near rubber	USPAT	OR	ON	2004/09/10 19:52
S25	18	(thermal or heat) with grease same silicon near rubber	USPAT	OR	ON	2004/09/10 20:12
S26	0	(thermal or heat) with grease same (epoxy with curing near agent with catalyst with coupling near agent)	USPAT	OR	ON	2004/09/10 20:14
S27	0	(thermal or heat) with grease same (epoxy with curing near agent with catalyst with coupling)	USPAT	OR	ON	2004/09/10 20:44
S28	10	epoxy with (mold$3 or encapsulat$3) and (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "7"	USPAT	OR	ON	2004/09/10 21:24

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S29	22	epoxy with (mold$3 or encapsulat$3) and (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "5"	USPAT	OR	ON	2004/09/10 20:52
S30	5	epoxy with (mold$3 or encapsulat$3) same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "5"	USPAT	OR	ON	2004/09/10 20:53
S31	7	epoxy with (mold$3 or encapsulat$3) same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "6"	USPAT	OR	ON	2004/09/10 20:55
S32	1	epoxy with (mold$3 or encapsulat$3) same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "8"	USPAT	OR	ON	2004/09/10 20:56
S33	2	epoxy with (mold$3 or encapsulat$3) same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "9"	USPAT	OR	ON	2004/09/10 20:57
S34	8	epoxy with (mold$3 or encapsulat$3) same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "10"	USPAT	OR	ON	2004/09/10 21:14
S35	41	("Cu" or copper) with coefficient near thermal near expansion with "17"	USPAT	OR	ON	2004/09/10 21:15
S36	0	("Cu" or copper) with coefficient near thermal near expansion with "17" near "ppm/.degree"	USPAT	OR	ON	2004/09/10 21:15
S37	19	("Cu" or copper) with coefficient near thermal near expansion with "17" near ppm$8	USPAT	OR	ON	2004/09/10 21:16
S38	26	epoxy same (mold$3 or encapsulat$3) and (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "10"	USPAT	OR	ON	2004/09/10 21:25
S39	2	epoxy same (mold$3 or encapsulat$3) and (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "10" near ppm$8	USPAT	OR	ON	2004/09/10 21:26
S40	1	epoxy same (mold$3 or encapsulat$3) and (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "4" near ppm$8	USPAT	OR	ON	2004/09/10 21:27

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S41	0	epoxy same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "4" near ppm$8	USPAT	OR	ON	2004/09/10 21:27
S42	0	epoxy same (mold$3 or encapsulat$3) with coefficient near thermal near expansion with "1" near ppm$8	USPAT	OR	ON	2004/09/10 21:27
S43	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "5" near ppm$8	USPAT	OR	ON	2004/09/10 21:28
S44	1	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "6" near ppm$8	USPAT	OR	ON	2004/09/10 21:28
S45	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "7" near ppm$8	USPAT	OR	ON	2004/09/10 21:28
S46	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "8" near ppm$8	USPAT	OR	ON	2004/09/10 21:28
S47	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "9" near ppm$8	USPAT	OR	ON	2004/09/10 21:29
S48	1	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "10" near ppm$8	USPAT	OR	ON	2004/09/10 21:29
S49	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "11" near ppm$8	USPAT	OR	ON	2004/09/10 21:29
S50	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "12" near ppm$8	USPAT	OR	ON	2004/09/10 21:29
S51	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "14" near ppm$8	USPAT	OR	ON	2004/09/10 21:29
S52	3	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "15" near ppm$8	USPAT	OR	ON	2004/09/10 21:31

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S53	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "4" near ppm$8	USPAT	OR	ON	2004/09/10 21:31
S54	1	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "3" near ppm$8	USPAT	OR	ON	2004/09/10 21:32
S55	0	epoxy with (mold$3 or encapsulat$3) and epoxy with coefficient near thermal near expansion with "2" near ppm$8	USPAT	OR	ON	2004/09/10 22:52
S56	4	silicon with coefficient near thermal near expansion with "2" near ppm$8	USPAT	OR	ON	2004/09/10 22:53
S57	1	silicon with (chip or die) and silicon with coefficient near thermal near expansion with "2" near ppm$8	USPAT	OR	ON	2004/09/10 22:54
S58	23	silicon with (chip or die) and silicon with coefficient near thermal near expansion with "3" near ppm$8	USPAT	OR	ON	2004/09/10 23:39
S59	1726	257/704	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 23:54
S60	2443	257/706	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 00:13
S61	1515	257/717	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 00:42
S62	1914	257/718	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 00:55
S63	1511	257/719	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 01:10

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S64	1155	257/720	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 01:11
S65	943	438/122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/11 01:12
S66	0	(semiconductor or die or chip or IC) same (heat near (sink or spread$3 or transfer or radiat$3) or cap or lid) and thermal near grease same silicon near rubber with particle	USPAT	OR	ON	2005/03/16 23:06
S67	0	(semiconductor or die or chip or IC) same (heat near (sink or spread$3 or transfer or radiat$3) or cap or lid) and thermal near grease and silicon near rubber with particle	USPAT	OR	ON	2005/03/16 23:07
S68	3	(semiconductor or die or chip or IC) same (heat near (sink or spread$3 or transfer or radiat$3) or cap or lid) and thermal near grease same silicon with particle	USPAT	OR	ON	2005/03/16 23:09
S69	1	(semiconductor or die or chip or IC) same (heat near (sink or spread$3 or transfer or radiat$3) or cap or lid) and thermal near grease same (silicon or silicone or "Si") with rubber with (particle or filler)	USPAT	OR	ON	2005/03/16 23:32
S70	0	(semiconductor or die or chip or IC) same (heat near (sink or spread$3 or transfer or radiat$3) or cap or lid) and thermal near grease same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34
S71	0	thermal near grease same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34
S72	0	thermal near (grease or compound) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34

S73	0	thermal near (grease or compound material) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:35
S74	0	thermal near (grease or compound or material or resin) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:36
S75	0	thermal near (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:47
S76	3	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:54
S77	0	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT; JPO	OR	ON	2005/03/17 00:35
S78	3646	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 19:14
S79	123	508/161	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 00:28
S80	1	thermal with (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT; JPO	OR	ON	2005/03/17 00:36

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S81	0	thermal with (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant with (mold$3 or encapsulat$3) near releas$3 near agent	USPAT; JPO	OR	ON	2005/09/01 13:18
S82	0	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue or mold$3 or encapsulat$3) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT	OR	OFF	2005/03/21 14:20
S83	0	(grease or compound or material or resin or adhesive or glue or mold$3 or encapsulat$3) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT	OR	OFF	2005/03/21 14:20
S84	0	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue or mold$3 or encapsulat$3) same epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant	USPAT	OR	OFF	2005/03/21 14:21
S85	0	(grease or compound or material or resin or adhesive or glue or mold$3 or encapsulat$3) same epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant	USPAT	OR	OFF	2005/03/21 14:21
S86	0	"6509622" and width with corner	USPAT; JPO	OR	OFF	2005/03/24 11:41
S87	0	"6509622" and corner	USPAT; JPO	OR	OFF	2005/03/24 11:40

S88	1	"6509622" and width	USPAT; JPO	OR	OFF	2005/03/24 11:41
S89	1	"20050161744"	US-PGPUB; USPAT	OR	OFF	2005/08/31 18:11
S90	3719	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 19:25
S91	3245	257/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 19:25
S92	4	thermal with (grease or compound or material or resin or adhesive or glue) and epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant same (mold$3 or encapsulat$3 or cover$3 with resin) same releas$3 near agent	USPAT; JPO	OR	ON	2005/09/01 13:26
S93	3	thermal with (grease or compound or material or resin or adhesive or glue) and epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant same (mold$3 or encapsulat$3 or cover$3 with resin) with releas$3 near agent	USPAT; JPO	OR	ON	2005/09/01 13:27
S94	4	thermal with (grease or compound or material or resin or adhesive or glue) and epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant same (mold$3 or encapsulat$3 or cover$3 with resin) with releas$3	USPAT; JPO	OR	ON	2005/09/01 13:38

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S95	0	thermal near (grease or compound or material or resin or adhesive or glue) and epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant same (mold$3 or encapsulat$3 or cover$3 with resin) with releas$3	USPAT; JPO	OR	ON	2005/09/01 13:38
S96	2	(thermal or heat) near (grease or compound or material or resin or adhesive or glue) and epoxy near resin same curing near agent same catalyst same coupling with agent same (fillers or particles) same flame near retardant same (mold$3 or encapsulat$3 or cover$3 with resin) with releas$3	USPAT; JPO	OR	ON	2005/09/01 13:39
S97	3	thermal near grease with (silicon or silicone) near rubber with (particles or filler or fill$3)	USPAT	OR	ON	2005/09/01 13:47
S98	5	thermal near grease same (silicon or silicone) near rubber with (particles or filler or fill$3)	USPAT	OR	ON	2005/09/01 13:48
S99	22	thermal near grease same (silicon or silicone) near rubber	USPAT	OR	ON	2005/09/01 13:55
S10 0	17	S99 not S98	USPAT	OR	ON	2005/09/01 13:48
S10 1	195	(thermal or heat or "Si" or silicon or silicone) near grease same (silicon or silicone) near rubber	USPAT	OR	ON	2005/09/01 13:56
S10 2	43	(thermal or heat or "Si" or silicon or silicone) near grease same (silicon or silicone) near rubber with (particles or filler or fill$3)	USPAT	OR	ON	2005/09/01 13:56
S10 3	38	S102 not S99	USPAT	OR	ON	2005/09/01 13:56
S10 4	0	"2002079573".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/13 15:04
S10 5	0	"2002079573"	US-PGPUB; USPAT	OR	OFF	2006/03/13 15:03
S10 6	72	257/718	US-PGPUB	OR	OFF	2006/03/13 15:03
S10 7	1	"20020079573".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/13 15:06
S10 8	2	"20020079573".pn. or "2003069263"	US-PGPUB; JPO	OR	OFF	2006/03/13 15:06

EAST Search History

S10 9	4	("6362530".pn. or "5917702".pn. or "6492724".pn. or "6309908". pn.) and (semiconductor or die or dice or chip or IC) with (packag$3 or mold$3 or encapsulat$3)	USPAT	OR	OFF	2006/03/13 15:59
S11 0	25	("3986251" | "4035830" | "4147889" | "4181249" | "4293587" | "4321617" | "4323914" | "4434434" | "4451972" | "4535219" | "4772935" | "4866505" | "5161728" | "5183972" | "5230924" | "5248079" | "5392982" | "5672548" | "5847929" | "5909056" | "5942794" | "5990418" | "6013109" | "6197619" | "6376907").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 16:08
S11 1	0	("6492724").URPN.	USPAT	OR	OFF	2006/03/13 16:08
S11 2	9	("4147889" | "4742024" | "5107329" | "5381039" | "5623394" | "5909056" | "5931222" | "5990418" | "6008536").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 16:14
S11 3	6	("6376907").URPN.	USPAT	OR	OFF	2006/03/13 16:13
S11 4	29	("5990418").URPN.	USPAT	OR	OFF	2006/03/13 16:17
S11 5	18	("4514752" | "4985753" | "5014115" | "5132875" | "5268533" | "5297006" | "5317107" | "5323294" | "5324888" | "5357673" | "5365402" | "5414214" | "5455457" | "5471366" | "5528456" | "5539151" | "5706579" | "5745344").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 16:22
S11 6	6	("2946681" | "3694699" | "4233645" | "4381818" | "4823863").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 16:30
S11 7	34	("5323294").URPN.	USPAT	OR	OFF	2006/03/13 16:30
S11 8	10	("4914551" | "5459352" | "5504652" | "5710459" | "5870285" | "5898571" | "5920458" | "5926371" | "5933324" | "6008536").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/13 16:49

S11 9	14	("6188578").URPN.	USPAT	OR	OFF	2006/03/13 16:51
S12 0	3534	257/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 19:09
S12 1	1483	257/704	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 19:30
S12 2	4	(semiconductor or die or dice or chip or IC) and mold$3 with (epoxy near resin) with curing near agent with catalyst with coupling near agent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 19:14
S12 3	2790	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 19:46
S12 4	943	257/720	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 20:02
S12 5	2	"6362530".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 20:19
S12 6	0	257/E23.119	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 20:22
S12 7	2	257/E23.087	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 20:22

S12 8	4	257/E23.101	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/13 20:22